



## TGD N-Channel Enhancement Mode Power MOSFET

**Description**

The TGD0203S uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

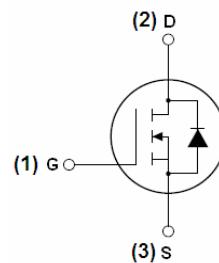
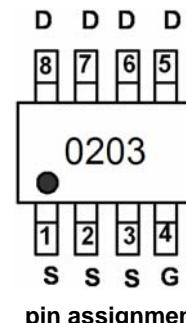
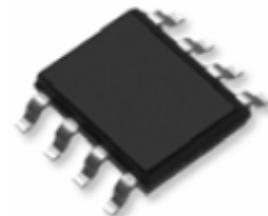
**General Features**

- $V_{DS} = 200V, I_D = 3.9A$
- $R_{DS(ON)} < 79m\Omega @ V_{GS}=10V$  (Typ:  $56m\Omega$ )
- High density cell design for ultra low  $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Low gate to drain charge to reduce switching losses

**Application**

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

**100%  $\Delta V_{ds}$  TESTED!**

**Schematic diagram****pin assignment****SOP-8 top view****Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
0203	0203S	SOP-8	Ø330mm	12mm	2500 units

**Absolute Maximum Ratings ( $T_A=25^\circ C$  unless otherwise noted)**

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	200	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	3.9	A
Drain Current-Continuous( $T_C=100^\circ C$ )	$I_D (100^\circ C)$	3	A
Pulsed Drain Current	$I_{DM}$	30	A
Maximum Power Dissipation	$P_D$	3	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

**Thermal Characteristic**

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	$R_{eJC}$	41.7	°C/W
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Electrical Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)

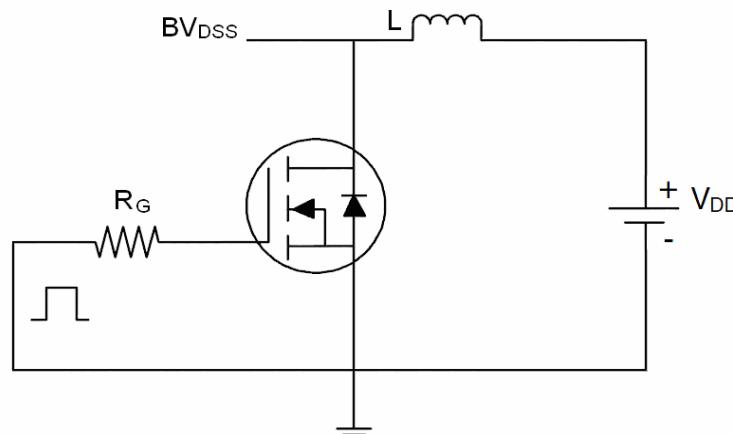
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	200	215	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=200\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2	3	4	V
Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=3.7\text{A}$	-	56	79	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=50\text{V}, I_{\text{D}}=3.9\text{A}$	7	-	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$		4200		PF
Output Capacitance	$C_{\text{oss}}$			163		PF
Reverse Transfer Capacitance	$C_{\text{rss}}$			75		PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=100\text{V}, I_{\text{D}}=2.2\text{A}$ $V_{\text{GS}}=10\text{V}, R_{\text{GEN}}=6.5\Omega$	-	15	-	nS
Turn-on Rise Time	$t_r$		-	13	-	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	26	-	nS
Turn-Off Fall Time	$t_f$		-	14	-	nS
Total Gate Charge	$Q_g$	$V_{\text{DS}}=100\text{V}, I_{\text{D}}=2.2\text{A},$ $V_{\text{GS}}=10\text{V}$	-	38	-	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	9	-	nC
Gate-Drain Charge	$Q_{\text{gd}}$		-	15	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note 3)</sup>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{s}}=3.7\text{A}$	-	-	1.2	V
Diode Forward Current <sup>(Note 2)</sup>	$I_{\text{s}}$		-	-	4	A

## Notes:

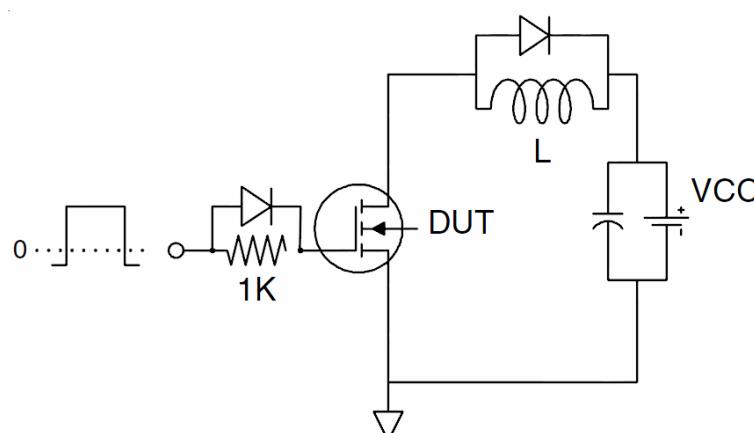
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

### Test Circuit

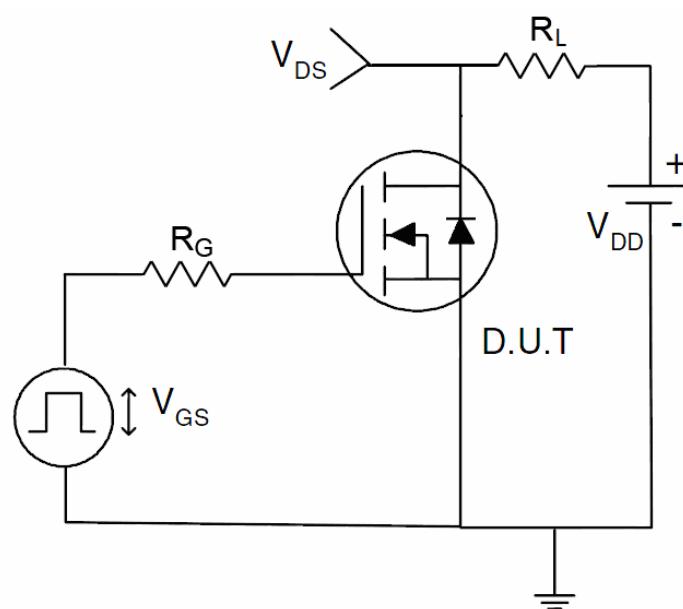
#### 1) E<sub>AS</sub> test Circuit



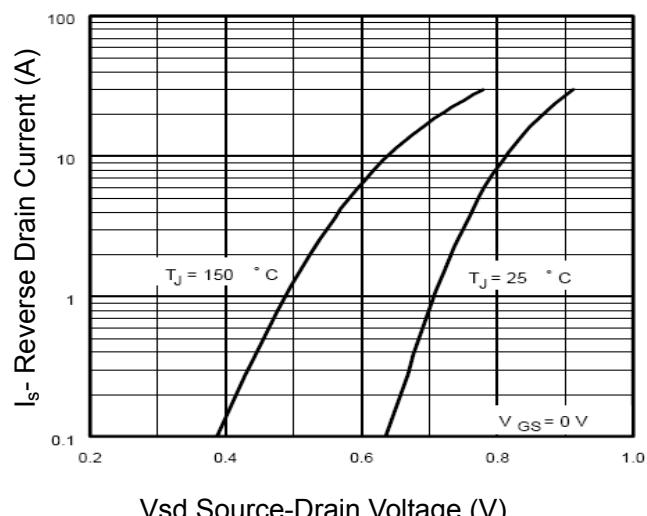
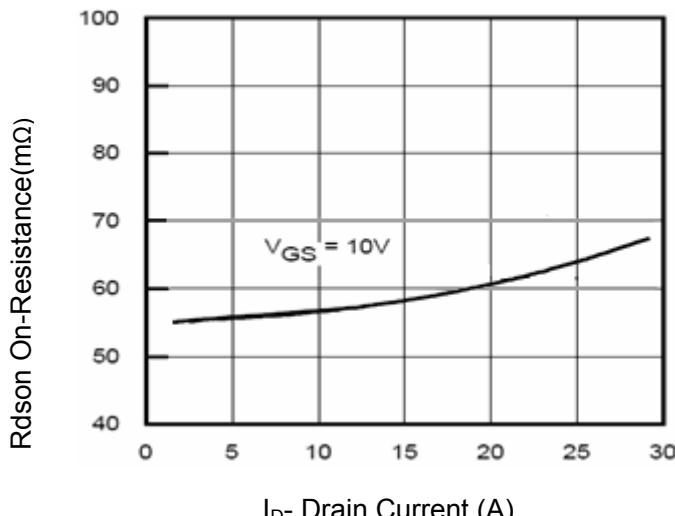
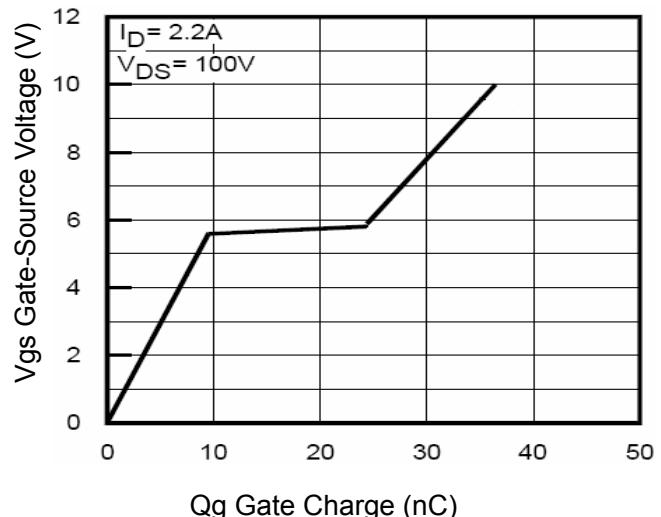
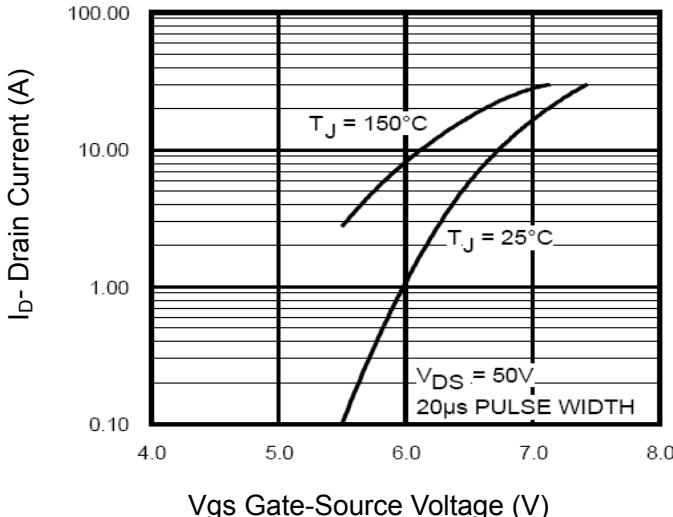
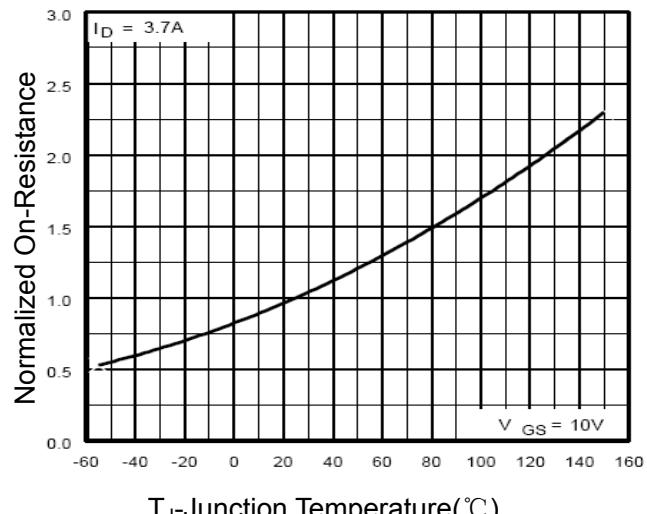
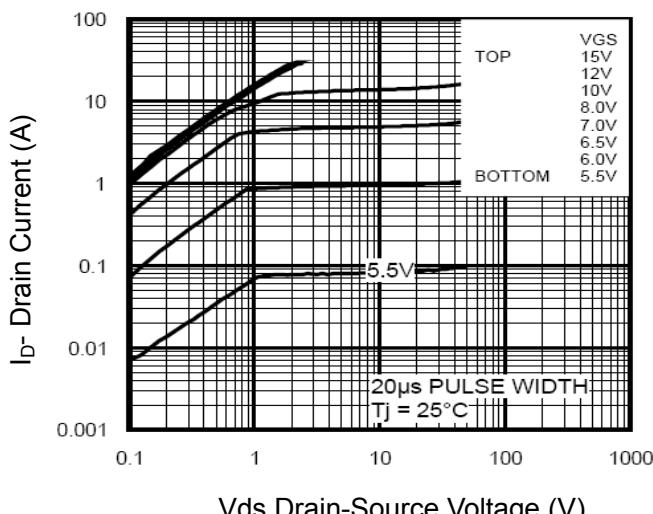
#### 2) Gate charge test Circuit

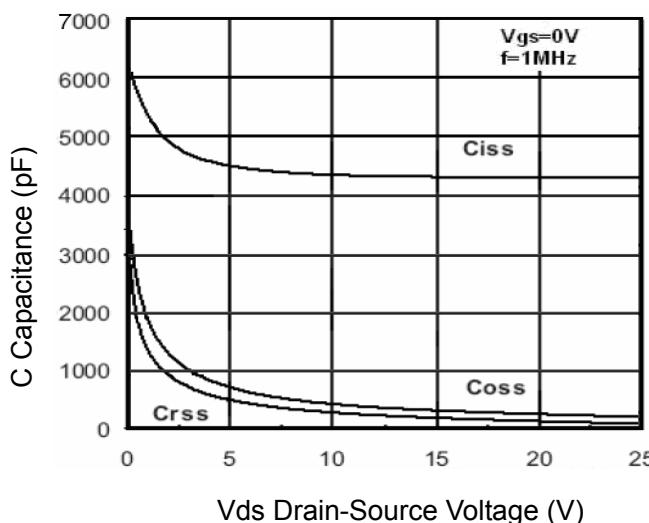


#### 3) Switch Time Test Circuit

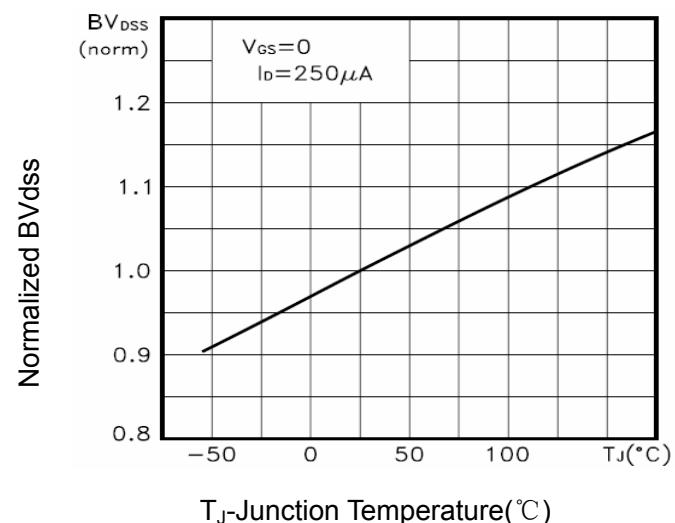


### Typical Electrical and Thermal Characteristics (Curves)

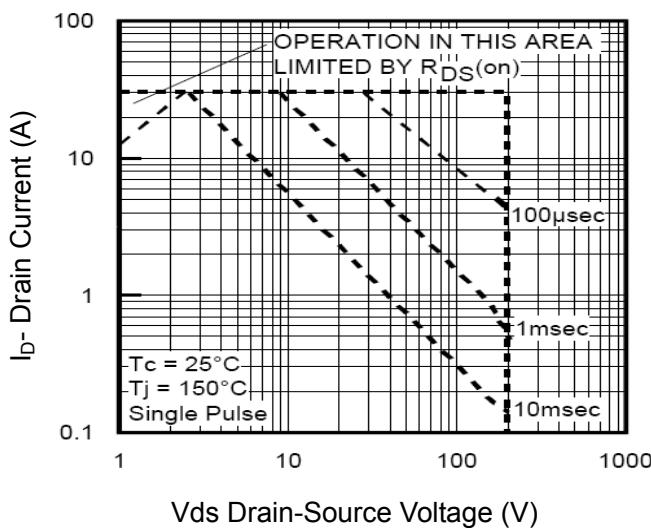




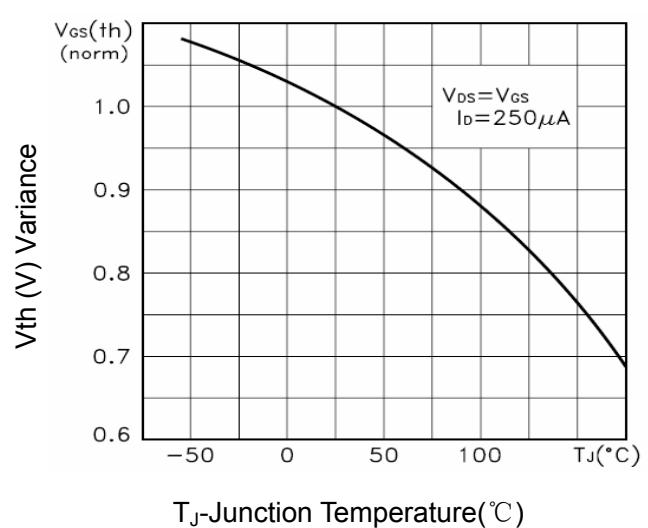
**Figure 7 Capacitance vs Vds**



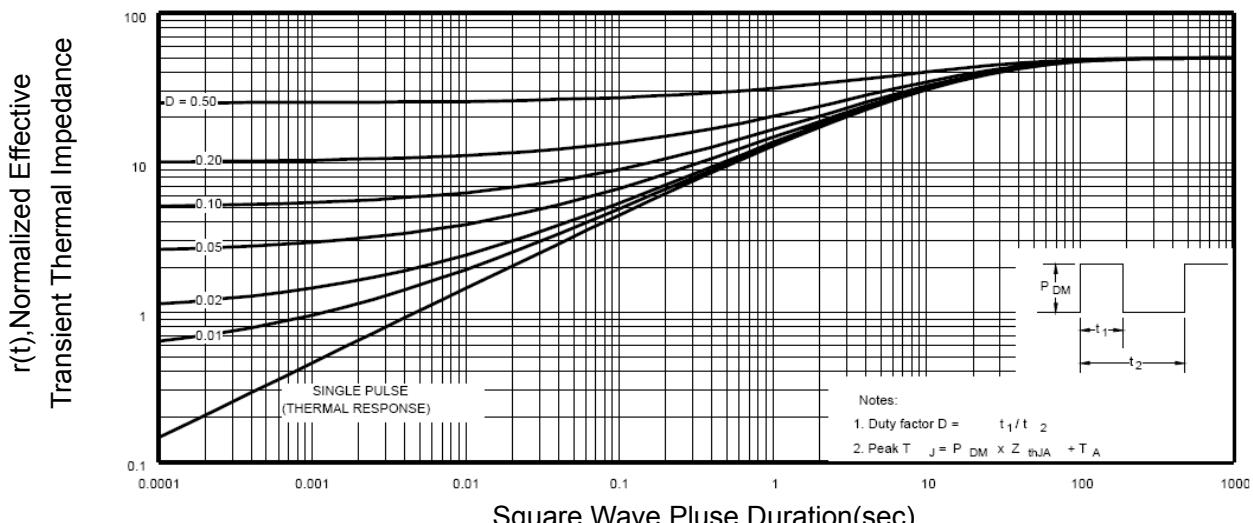
**Figure 9  $BV_{dss}$  vs Junction Temperature**



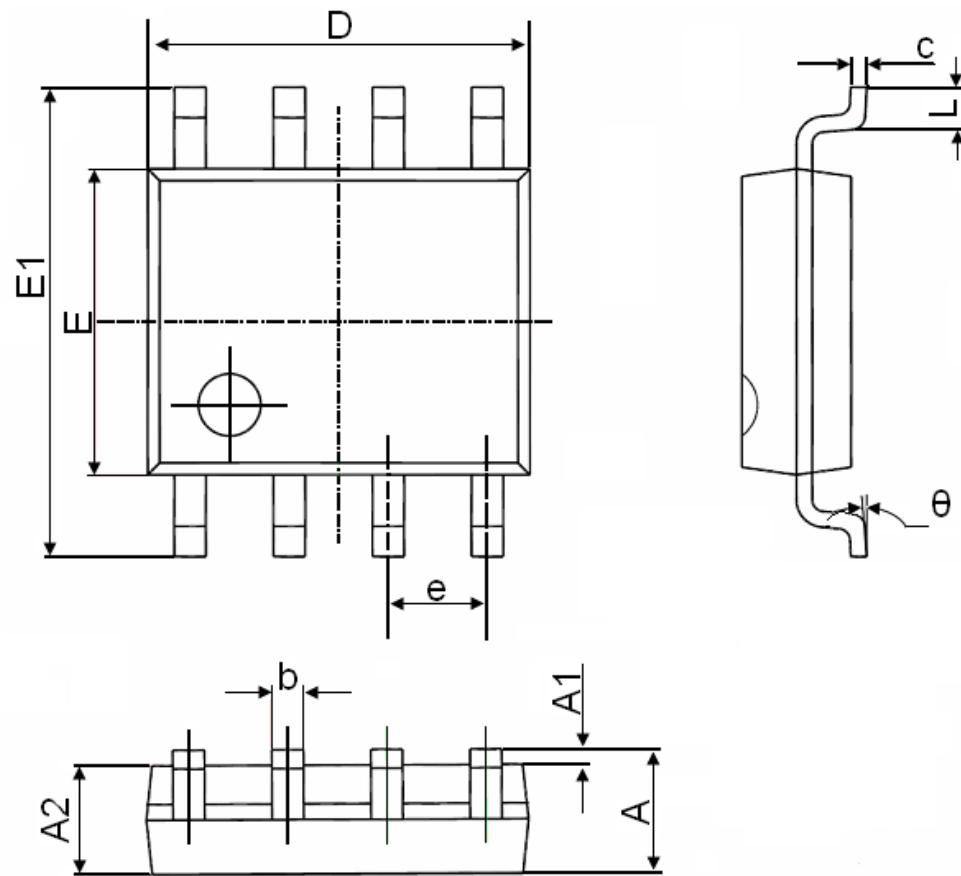
**Figure 8 Safe Operation Area**



**Figure 10  $V_{gs(th)}$  vs Junction Temperature**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

**SOP-8 Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°